SVENSK STANDARD SS-EN 62680-1-2

Fastställd	Utgåva	Sida	Ansvarig kommitté
2017-06-14	1	1 (1+471)	SEK TK 100

Gränssnitt för seriebuss för datakommunikation (USB) – Del 1-2: Gemensamma komponenter – Specifikation för strömförsörjning (USB PD)

Universal serial bus interfaces for data and power – Part 1-2: Common components – USB Power Delivery specification

Som svensk standard gäller europastandarden EN 62680-1-2:2017. Den svenska standarden innehåller den officiella engelska språkversionen av EN 62680-1-2:2017.

Nationellt förord

Europastandarden EN 62680-1-2:2017

består av:

– **europastandardens ikraftsättningsdokument,** utarbetat inom CENELEC

– **IEC 62680-1-2, First edition, 2016 - Universal serial bus interfaces for data and power - Part 1-2: Common components - USB Power Delivery specification**

utarbetad inom International Electrotechnical Commission, IEC.

ICS 29.220.00; 33.120.00; 35.200.00

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EUROPEAN STANDARD

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EUROPÄISCHE NORM

EN 62680-1-2

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ICS 29.220; 33.120; 35.200

English Version

Universal serial bus interfaces for data and power - Part 1-2: Common components - USB Power Delivery specification (IEC 62680-1-2:2016)

Interfaces bus série universel (USB) pour les données et l'alimentation électrique - Partie 1-2 : Composants communs - Spécification USB pour la fourniture de courant (IEC 62680-1-2:2016)

Schnittstellen des Universellen Seriellen Busses für Daten und Energie - Teil 1-2: Gemeinsame Komponenten - USB Stromversorgungs-Spezifikation (IEC 62680-1-2:2016)

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Ref. No. EN 62680-1-2:2017 E

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European foreword

The text of document 100/2728/CDV, future edition 1 of IEC 62680-1-2, prepared by IEC/TC 100 “Audio, video and multimedia systems and equipment” was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62680-1-2:2017.

The following dates are fixed:

• latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2017-09-13
• latest date by which the national standards conflicting with the document have to be withdrawn	(dow)	2019-12-13

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UNIVERSAL SERIAL BUS INTERFACES FOR DATA AND POWER

Part 1-2: Common components – USB Power Delivery specification

FOREWORD

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The text of this standard was prepared by the USB Implementers Forum (USB-IF). The structure and editorial rules used in this publication reflect the practice of the organization which submitted it.

The text of this standard is based on the following documents:

CDV	Report on voting
100/2728/CDV	100/2729/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

A list of all parts in the IEC 62680 series, published under the general title *Universal serial bus interfaces for data and power*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

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INTRODUCTION

The IEC 62680 series is based on a series of specifications that were originally developed by the USB Implementers Forum (USB-IF). These specifications were submitted to the IEC under the auspices of a special agreement between the IEC and the USB-IF.

This standard is the USB-IF publication USB Power Delivery Specification Revision 3.0 V.1.0.

The USB Implementers Forum, Inc.(USB-IF) is a non-profit corporation founded by the group of companies that developed the Universal Serial Bus specification. The USB-IF was formed to provide a support organization and forum for the advancement and adoption of Universal Serial Bus technology. The Forum facilitates the development of high-quality compatible USB peripherals (devices), and promotes the benefits of USB and the quality of products that have passed compliance testing.

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Universal Serial Bus Power Delivery Specification

Revision 3.0, V1.0. 11 December 2015

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Revision History

Revision	Version	Comments	Issue Date
1.0	1.0	Initial release Revision 1.0	5 July, 2012
1.0	1.1	Including errata through 31-October-2012	31 October 2012
1.0	1.2	Including errata through 26-June-2013	26 June, 2013
1.0	1.3	Including errata through 11-March-2014	11 March 2014
2.0	1.0	Initial release Revision 2.0	11 August 2014
2.0	1.1	Including errata through 7-May 2015	7 May 2015
3.0	1.0	Initial release Revision 3.0	11 December 2015

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1 Introduction

USB has evolved from a data interface capable of supplying limited power to a primary provider of power with a data interface. Today many devices charge or get their power from USB ports contained in laptops, cars, aircraft or even wall sockets. USB has become a ubiquitous power socket for many small devices such as cell phones, MP3 players and other hand-held devices. Users need USB to fulfill their requirements not only in terms of data but also to provide power to, or charge, their devices simply, often without the need to load a driver, in order to carry out “traditional” USB functions.

There are however, still many devices which either require an additional power connection to the wall, or exceed the USB rated current in order to operate. Increasingly, international regulations require better energy management due to ecological and practical concerns relating to the availability of power. Regulations limit the amount of power available from the wall which has led to a pressing need to optimize power usage. The USB Power Delivery Specification has the potential to minimize waste as it becomes a standard for charging devices that are not satisfied by ***[USBBC 1.2]***.

Wider usage of wireless solutions is an attempt to remove data cabling but the need for “tethered” charging remains. In addition, industrial design requirements drive wired connectivity to do much more over the same connector.

USB Power Delivery is designed to enable the maximum functionality of USB by providing more flexible power delivery along with data over a single cable. Its aim is to operate with and build on the existing USB ecosystem; increasing power levels from existing USB standards, for example Battery Charging, enabling new higher power use cases such as USB powered Hard Disk Drives (HDDs) and printers.

With USB Power Delivery the power direction is no longer fixed. This enables the product with the power (Host or Peripheral) to provide the power. For example, a display with a supply from the wall can power, or charge, a laptop. Alternatively, USB power bricks or chargers are able to supply power to laptops and other battery powered devices through their, traditionally power providing, USB ports.

USB Power Delivery enables hubs to become the means to optimize power management across multiple peripherals by allowing each device to take only the power it requires, and to get more power when required for a given application. For example battery powered devices can get increased charging current and then give it back temporarily when the user’s HDD requires spinning up. ***Optionally*** the hubs can communicate with the PC to enable even more intelligent and flexible management of power either automatically or with some level of user intervention.

USB Power Delivery allows Low Power cases such as headsets to negotiate for only the power they require. This provides a simple solution that enables USB devices to operate at their optimal power levels.

The Power Delivery Specification, in addition to providing mechanisms to negotiate power also can be used as a side-band channel for standard and vendor defined messaging. Power Delivery enables alternative modes of operation by providing the mechanisms to discover, enter and exit Alternate Modes. The specification also enables discovery of cable capabilities such as supported speeds and current levels.

1.1 Overview

This specification defines how USB Devices may negotiate for more current and/or higher or lower voltages over the USB cable (using the USB Type-C CC wire as the communications

channel) than are defined in the *[USB 2.0]*, *[USB 3.1]*, *[USB Type-C 1.2]* or *[USBBC 1.2]* specifications. It allows Devices with greater power requirements than can be met with today's specification to get the power they require to operate from V_{BUS} and negotiate with external power sources (e.g. wall warts). In addition, it allows a Source and Sink to swap power roles such that a Device could supply power to the Host. For example, a display could supply power to a notebook to charge its battery.

The USB Power Delivery Specification is guided by the following principles:

1) Works seamlessly with legacy USB Devices
2) Compatible with existing spec-compliant USB cables
3) Minimizes potential damage from non-compliant cables (e.g. 'Y' cables etc.)
4) Optimized for low-cost implementations

This specification defines mechanisms to discover, enter and exit Modes defined either by a standard or by a particular vendor. These Modes can be supported either by the Port Partner or by a cable connecting the two Port Partners.

The specification defines mechanisms to discover the capabilities of cables which can communicate using Power Delivery.

This specification adds a mechanism to swap the data roles such that the upstream facing Port becomes the downstream facing Port and vice versa. It also enables a swap of the end supplying V_{CONN} to a powered cable.

1.2 Purpose

The USB Power Delivery specification defines a power delivery system covering all elements of a USB system including: Hosts, Devices, Hubs, Chargers and cable assemblies. This specification describes the architecture, protocols, power supply behavior, connectors and cabling necessary for managing power delivery over USB at up to 100W. This specification is intended to be fully compatible and extend the existing USB infrastructure. It is intended that this specification will allow system OEMs, power supply and peripheral developers adequate flexibility for product versatility and market differentiation without losing backwards compatibility.

USB Power Delivery is designed to operate independently of the existing USB bus defined mechanisms used to negotiate power which are:

- *[USB 2.0]*, *[USB 3.1]* in band requests for high power interfaces.
- *[USBBC 1.2]* mechanisms for supplying higher power (not mandated by this specification).
- *[USB Type-C 1.2]* mechanisms for supplying higher power

Initial operating conditions remain the USB Default Operation as defined in *[USB 2.0]*, *[USB 3.1]*, *[USB Type-C 1.2]* or *[USBBC 1.2]*.

- The DFP sources *vSafe5V* over V_{BUS}.
- The UFP consumes power from V_{BUS}.

1.3 Scope

This specification is intended as an extension to the existing *[USB 2.0]*, *[USB 3.1]*, *[USB Type-C 1.2]* and *[USBBC 1.2]* specifications. It addresses only the elements required to implement USB Power Delivery. It is targeted at power supply vendors, manufacturers of *[USB 2.0]*, *[USB 3.1]*, *[USB Type-C 1.2]* and *[USBBC 1.2]* Platforms, Devices and cable assemblies.

Normative information is provided to allow interoperability of components designed to this specification. Informative information, when provided, may illustrate possible design implementation.